

In the top left corner, there are several decorative geometric shapes, including triangles and hexagons, outlined in red.

➤ Building the Adaptable Intelligent World

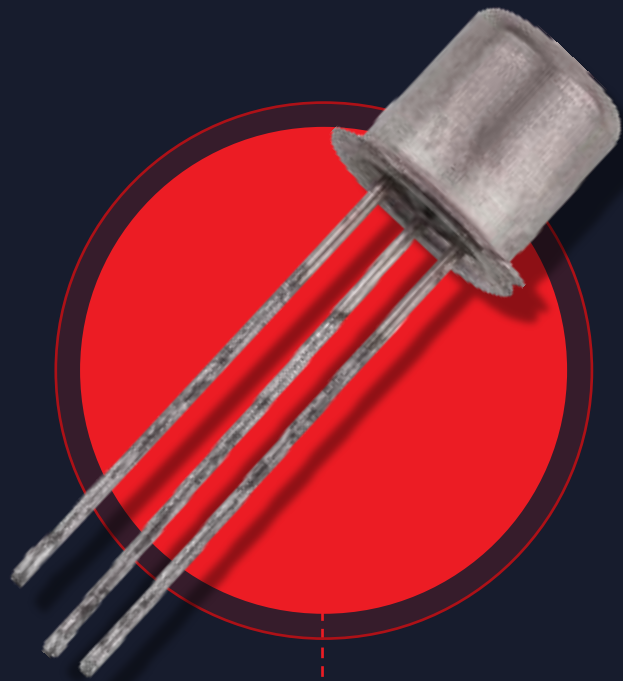
Kirk Saban
Senior Director, Product & Technical Marketing

Under Embargo Until 10/2 @ 9AM PST





**➤ Disruptive
Innovation**



Transistor

1940s





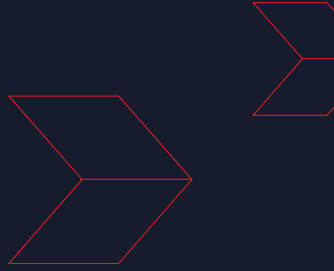
Computing

1970s



Distributed Computing

1990s



➤ Today's Developer Needs

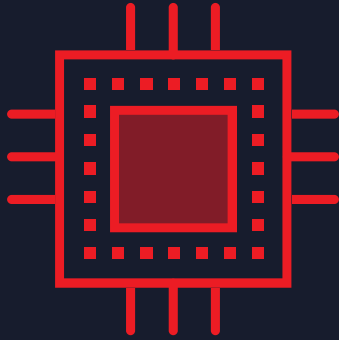
Software programmability

Performance for a diverse
range of applications

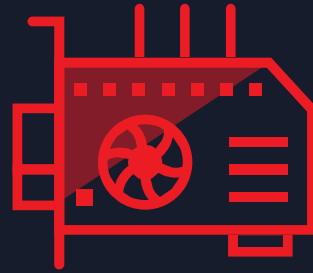
Adaptability to keep pace
with rapid innovation



Today's Solutions

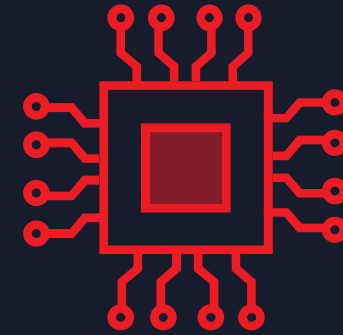


CPUs

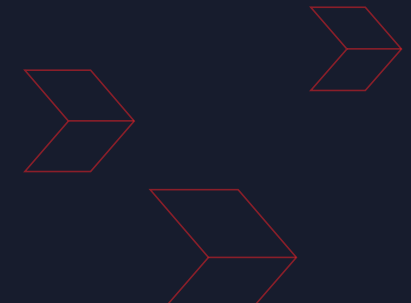


**Fixed Function
Accelerators**

ASICs/ASSPs/GPUs

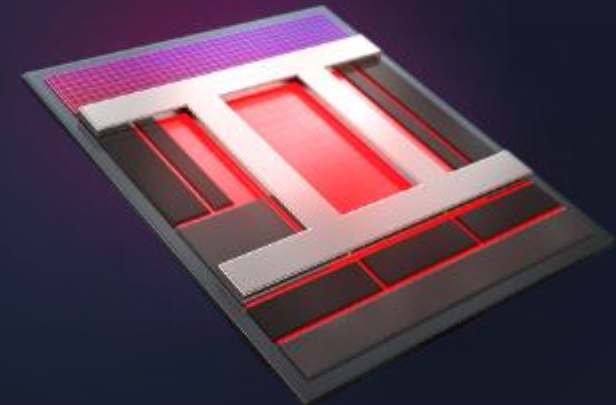


FPGAs

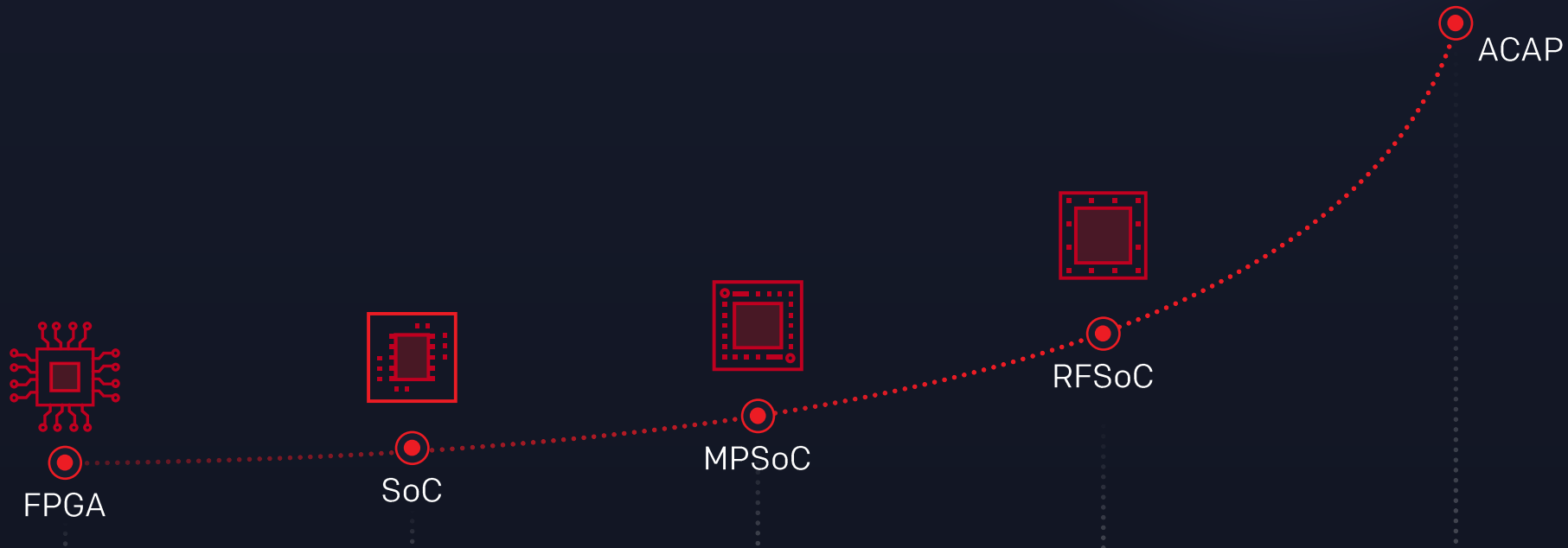


➤ Disruptive Innovation Needed: Enter ACAP

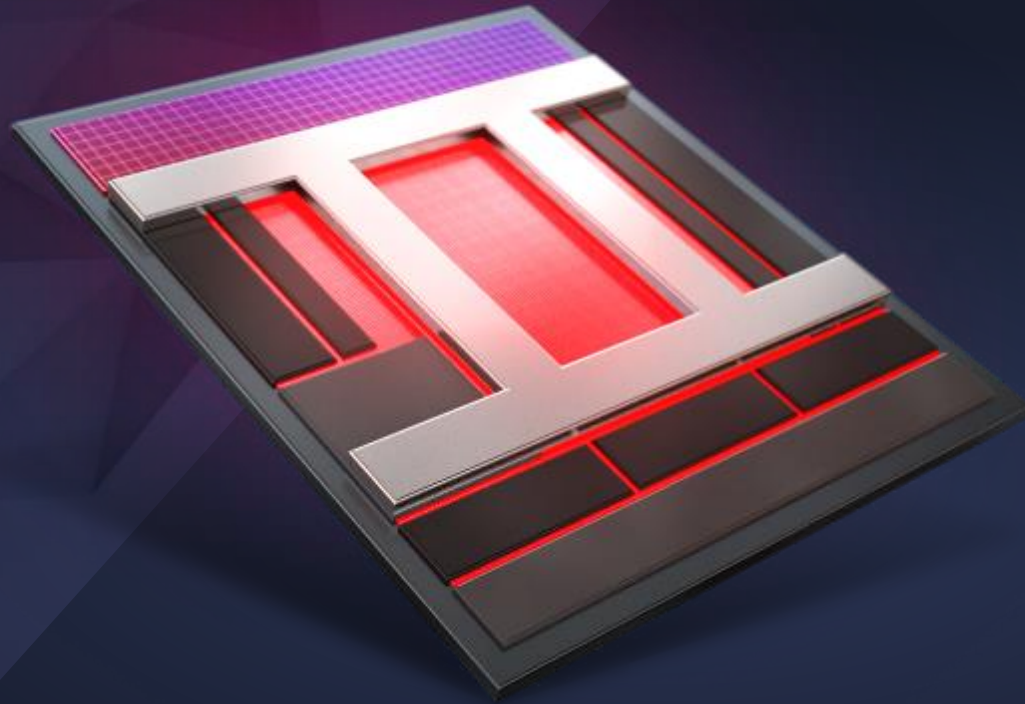
A new class of devices for today's challenges



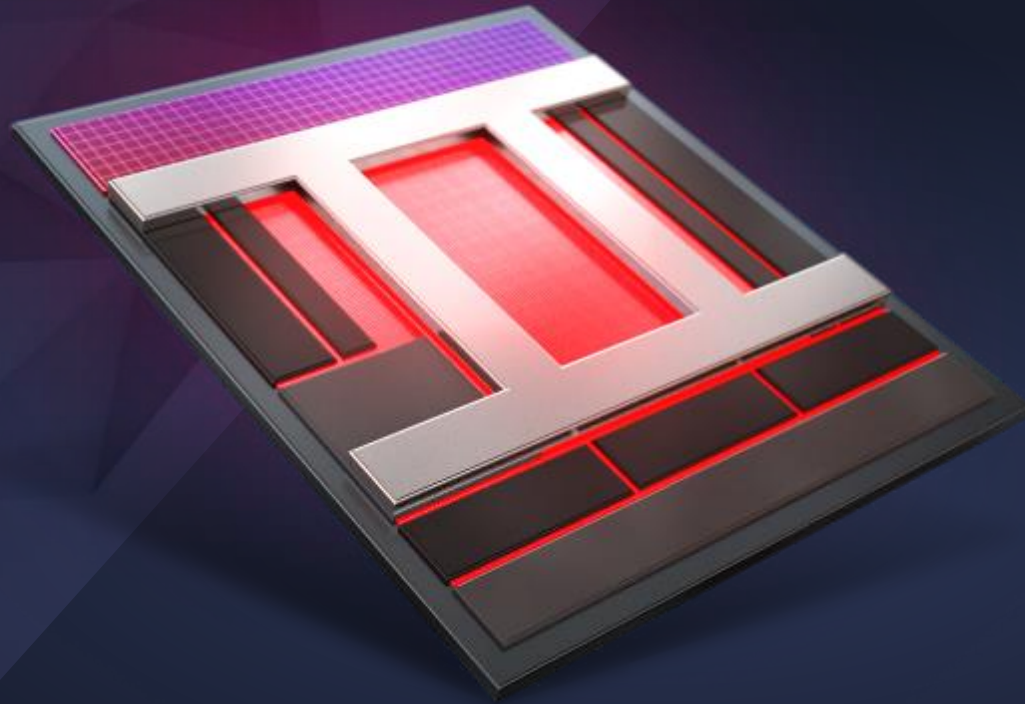
Software Programmability



Device Category

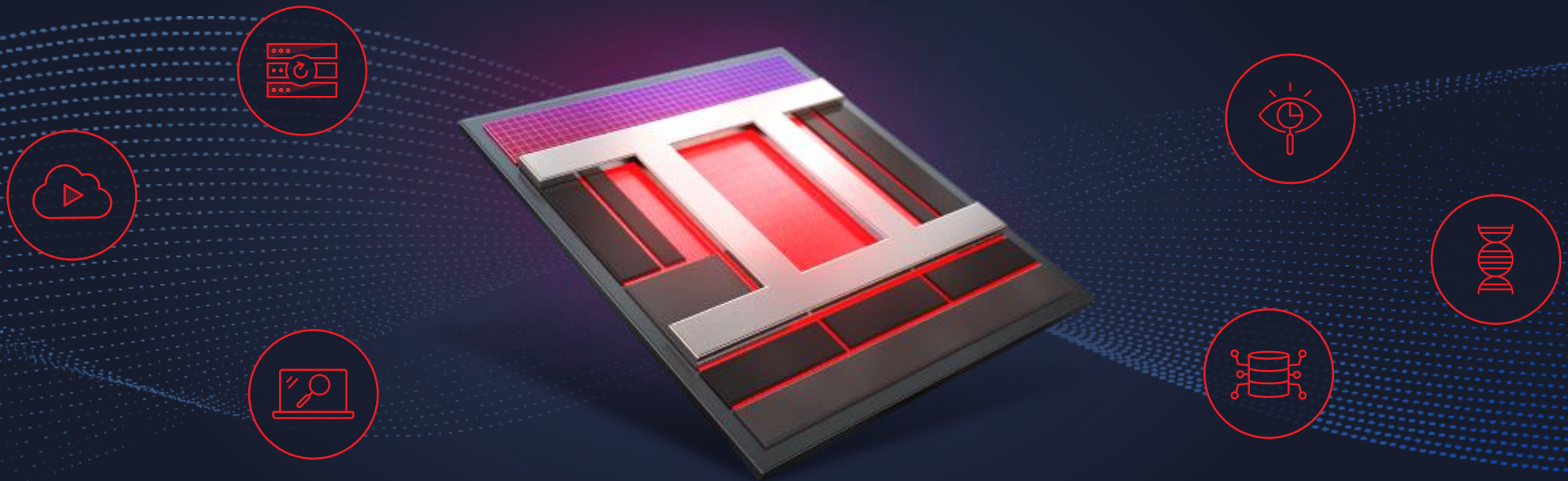


ACAP



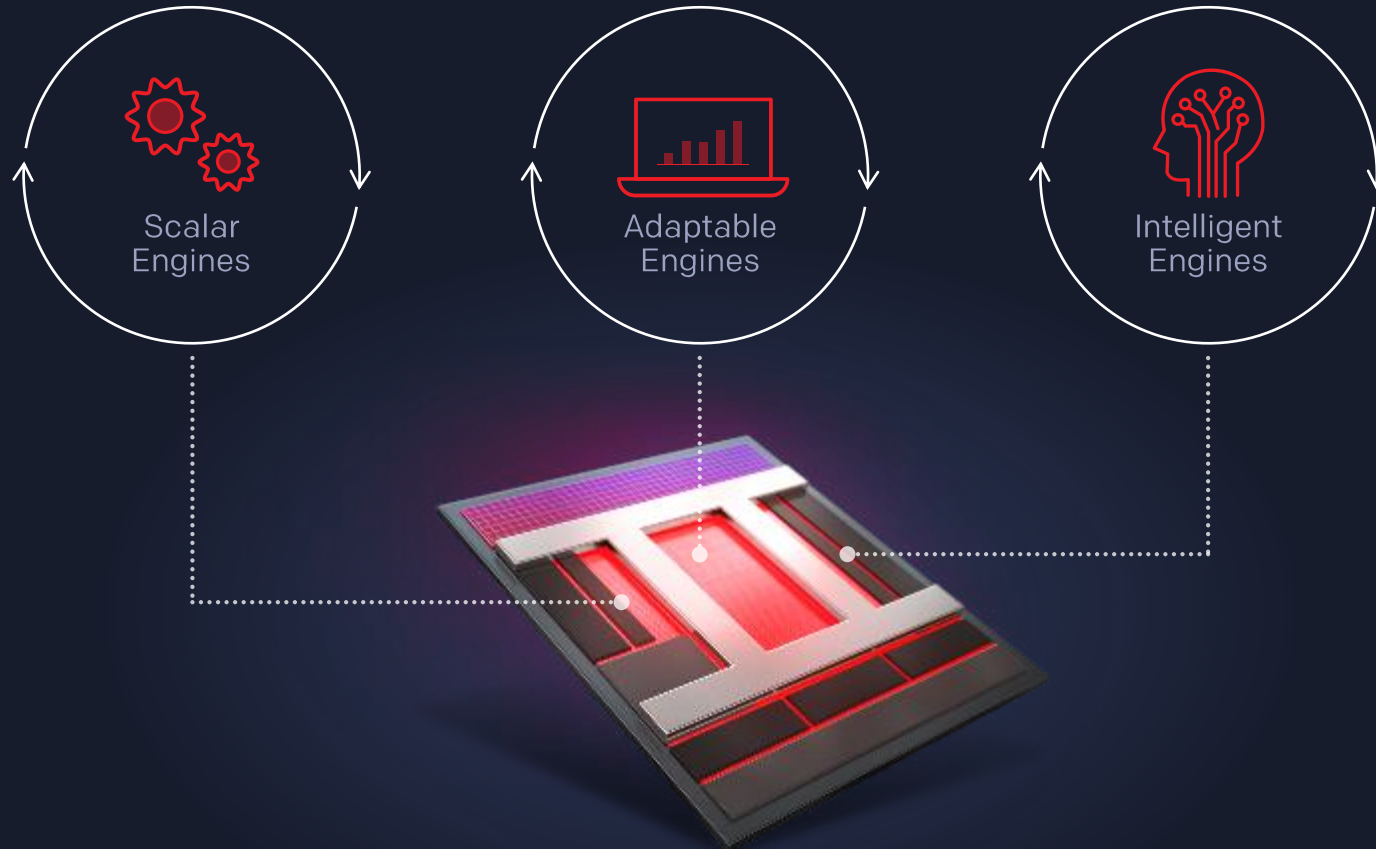
Adaptive Compute Acceleration Platform

Adaptive



Adaptive Hardware for
Domain-specific Applications

Compute Acceleration



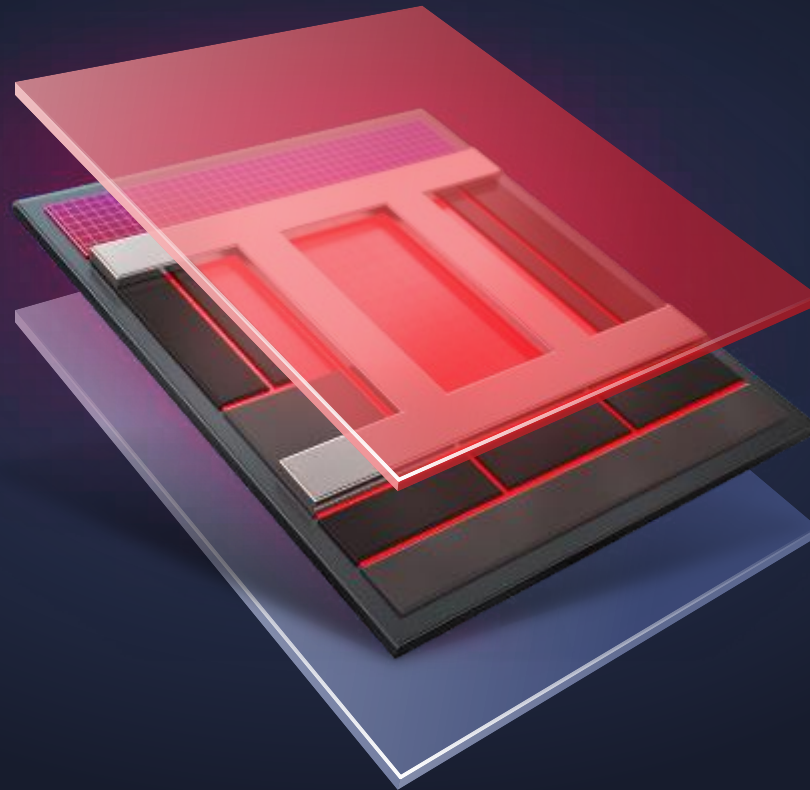
Platform

ENABLING:

Data Scientists

SW App Developers

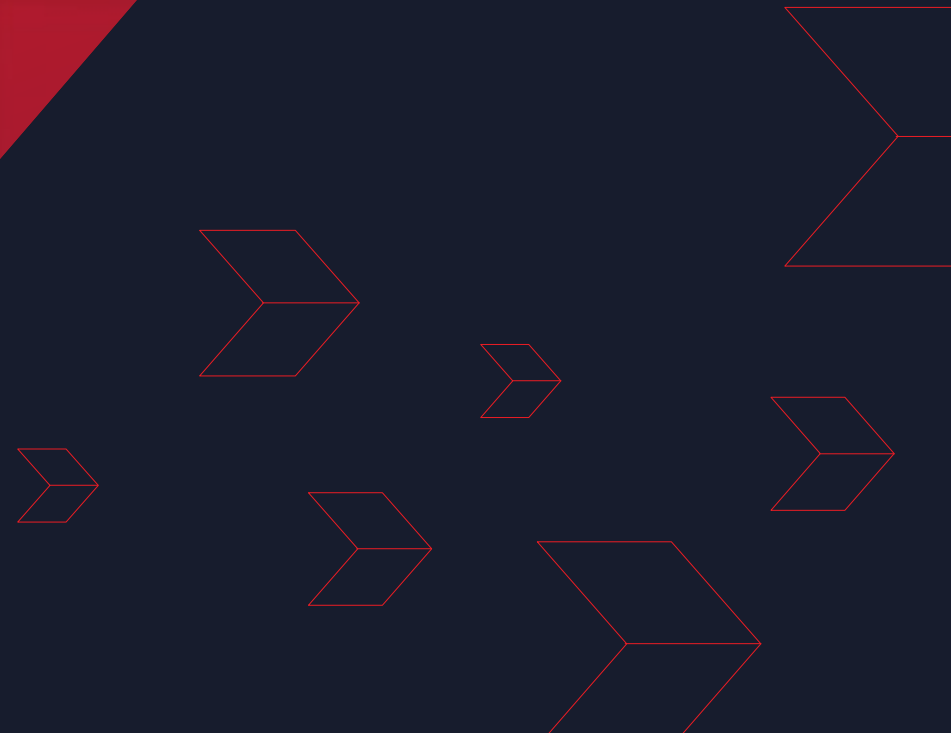
HW Developers

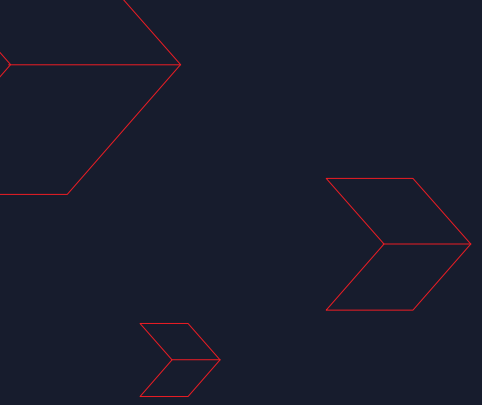


.....● Development Tools
.....● HW/SW Libraries
.....● Run-time Stack

.....● SW Programmable
.....● Silicon Infrastructure

Introducing the Industry's First ACAP





VERSATILE



UNIVERSAL





XILINX®
VERSAL™

The Industry's First ACAP

Heterogeneous Acceleration

For Any Application

For Any Developer



7nm
FinFET



Versal ACAP Technology Tour



Scalar Processing Engines



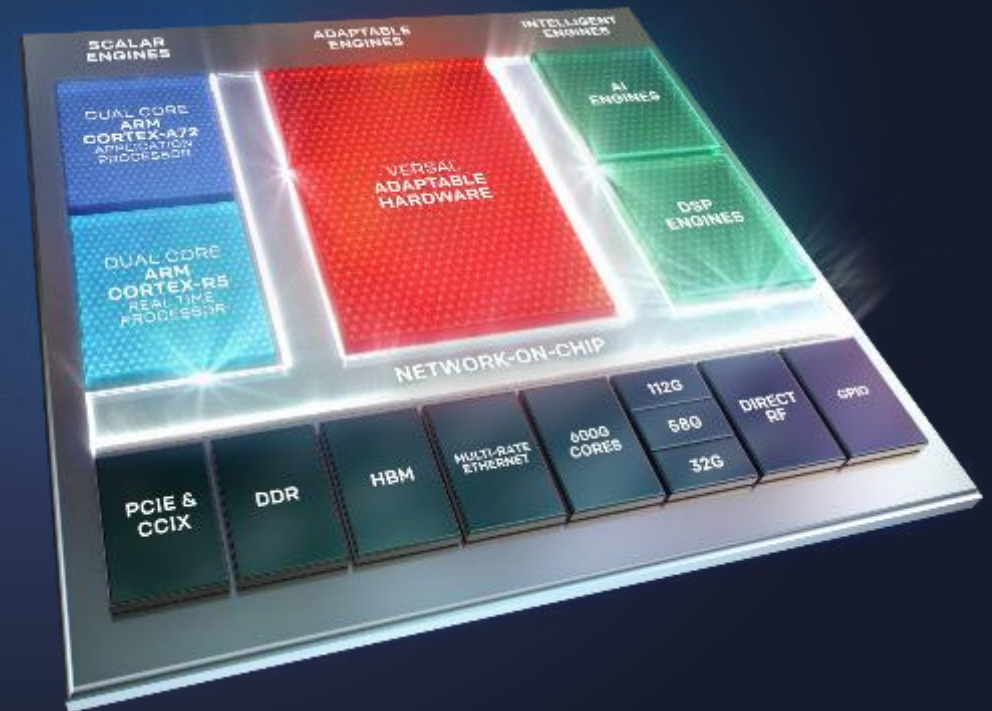
Adaptable Hardware Engines



Intelligent Engines
SW Programmable, HW Adaptable



Breakout Integration of Advanced
Protocol Engines

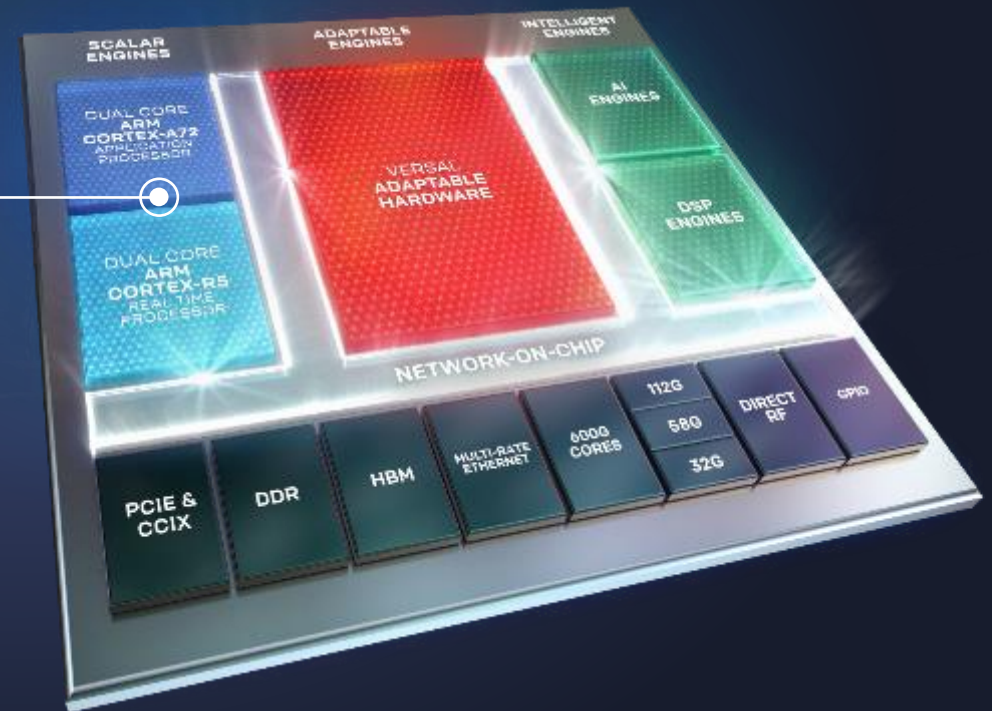


Scalar Processing Engines

Arm Cortex-A72
Application Processor

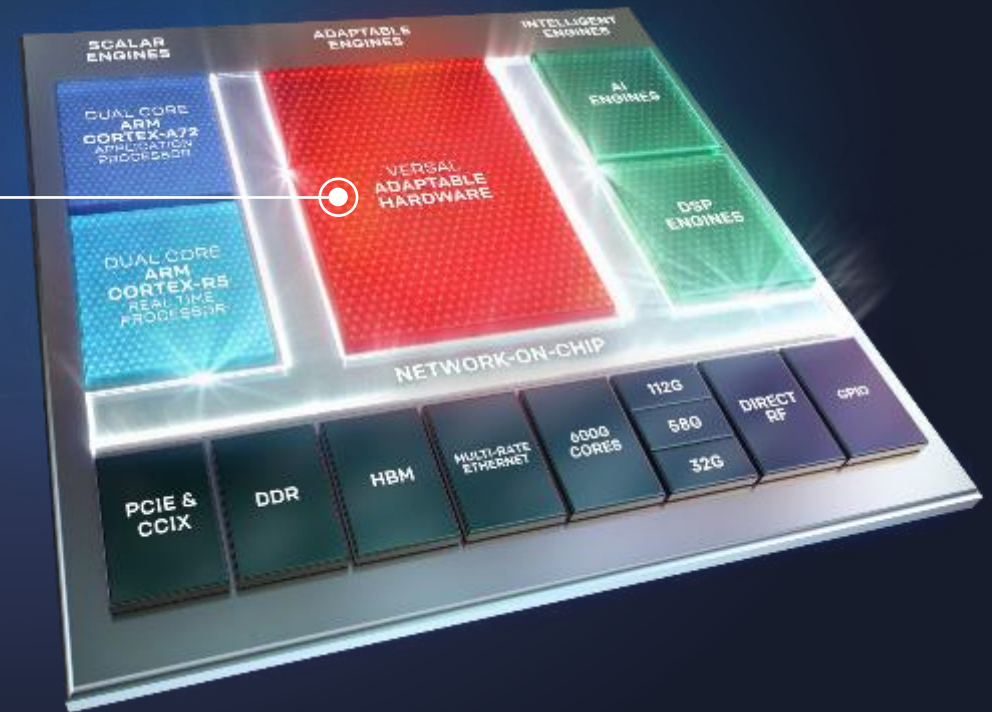
Arm Cortex-R5
Real-Time Processor

Platform Management Controller



Adaptable Hardware Engines

Re-architected foundational HW fabric for greater compute density
Enables custom memory hierarchy
8X Faster Dynamic Reconfiguration ("on-the-fly")



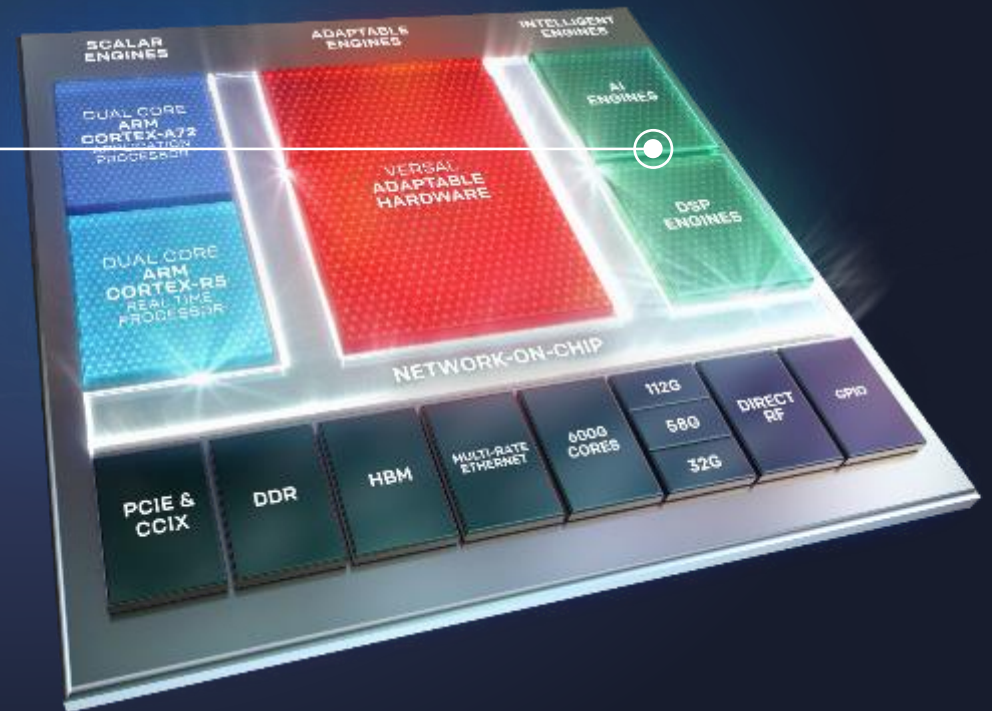
Intelligent Engines

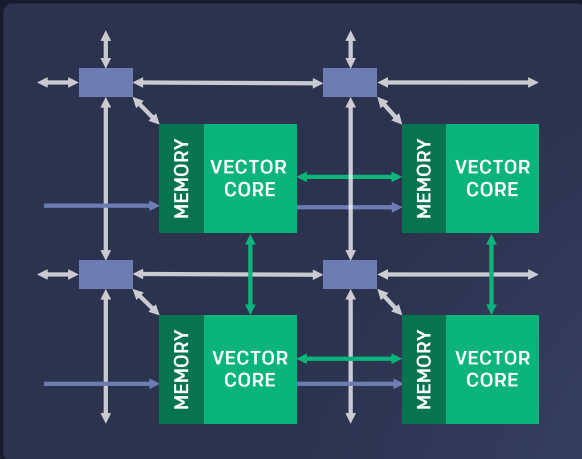
DSP Engines

High-precision floating point & low latency
Granular control for customized datapaths

AI Engines

High throughput, low latency, and power efficient
Ideal for AI inference and advanced signal processing

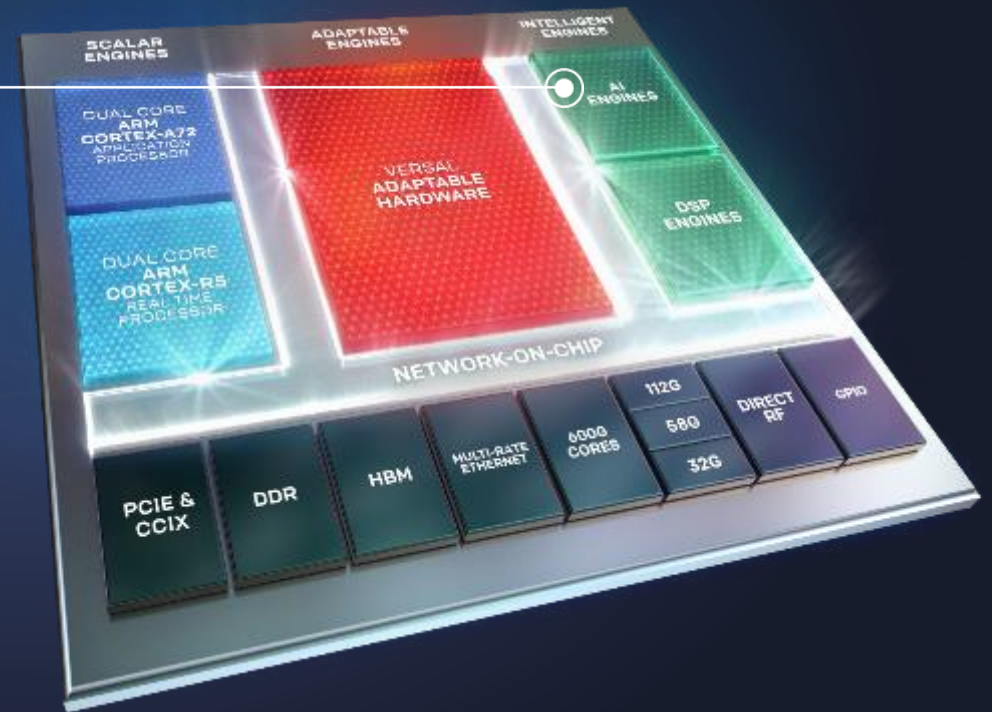


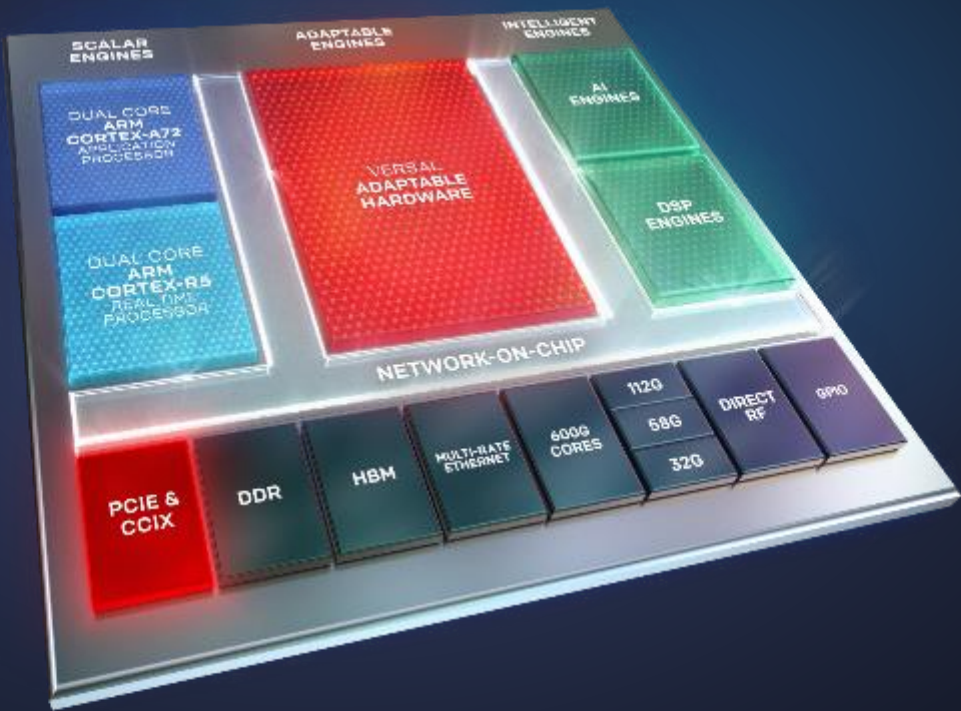


AI Engines

Optimized for AI Inference and Advanced Signal Processing Workloads

- >1GHz VLIW/SIMD vector processor cores
- Massive array of interconnected cores with local memory
- Tightly coupled to adaptable hardware enabling custom memory hierarchy
- Software programmable with hardware adaptability

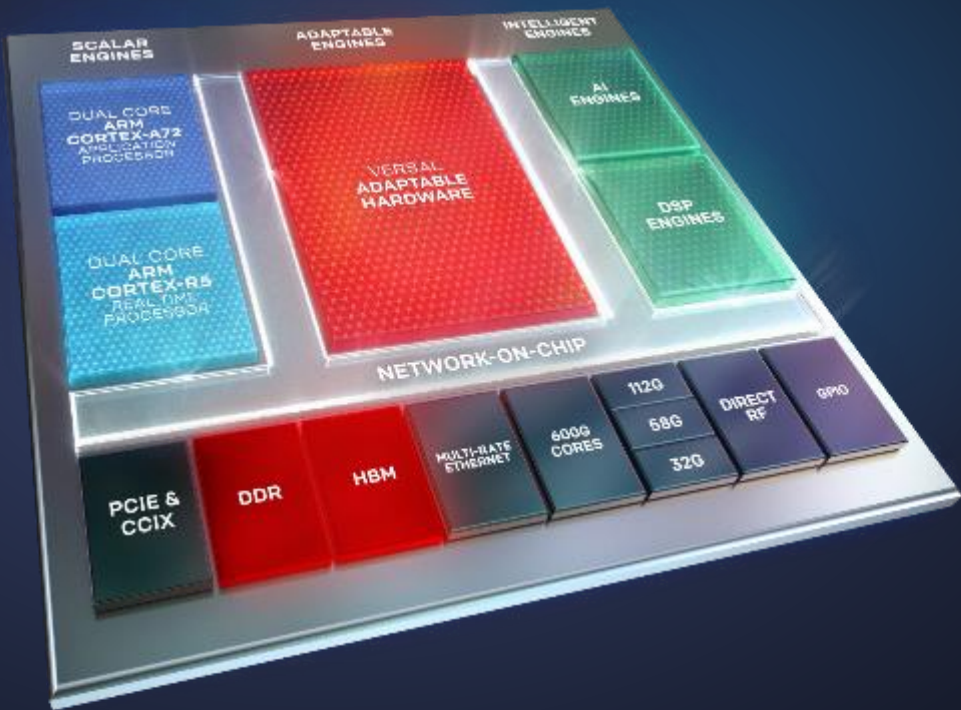




Integrated Host Interfaces

- PCIe Gen4x16
- Integrated AXI-DMA
- CCIX for seamless acceleration of server-class CPUs

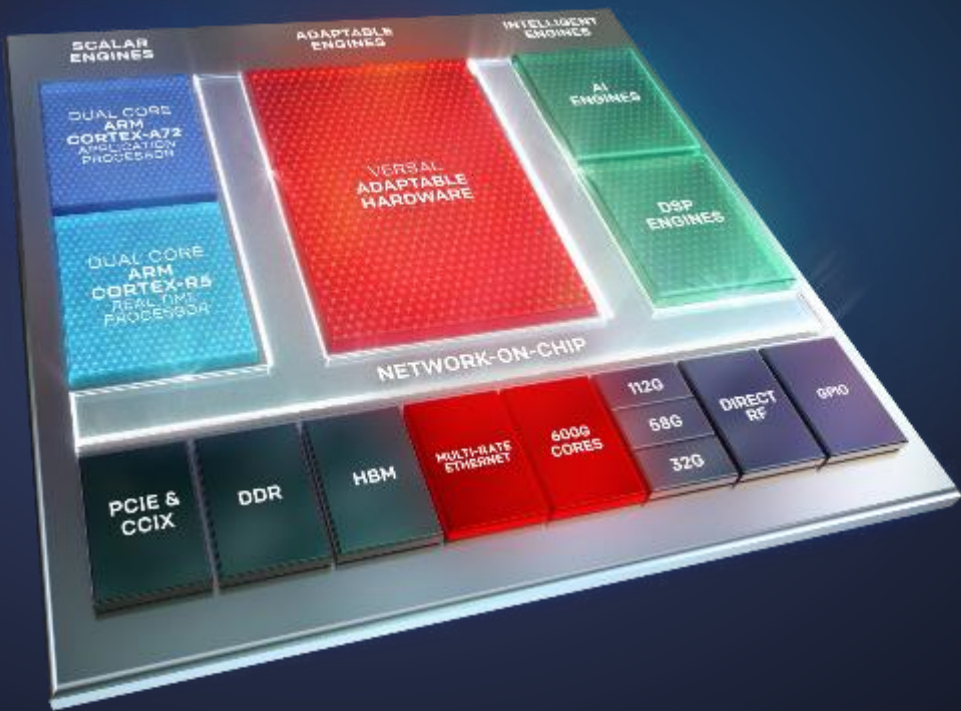




Scalable, Integrated Memory Controllers

- DDR4-3200
- LPDDR4-4266
- High Bandwidth Memory (HBM)

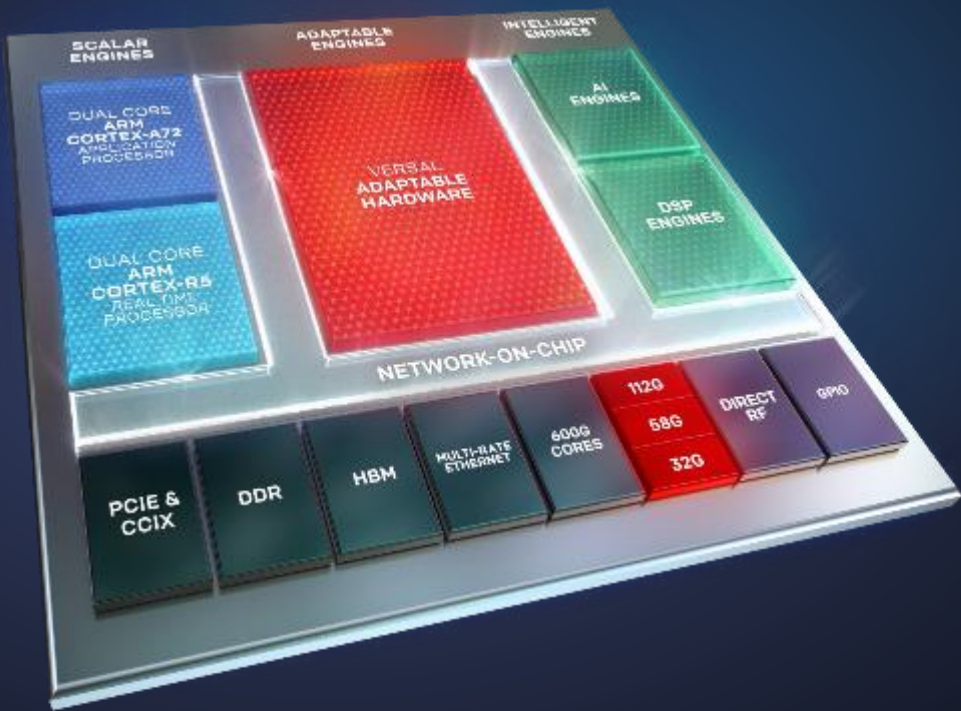




Integrated Protocol Engines

- 100G Multirate Ethernet
- 600G Ethernet and Interlaken
- 600G Cryptographic Engines (AES/IPSEC/MACSEC)

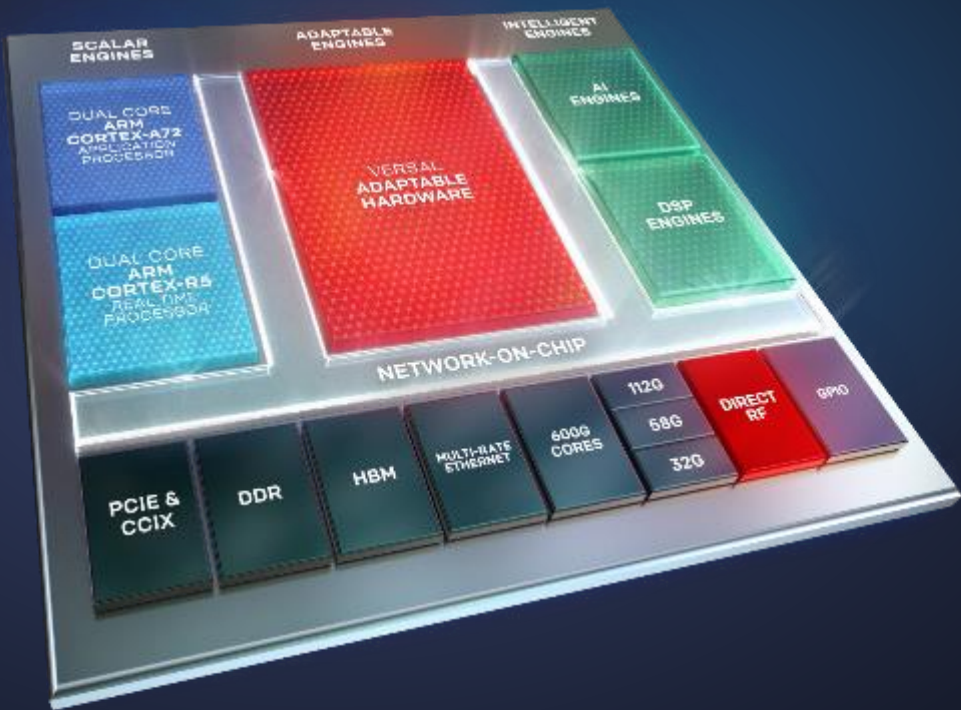




Broadest Range of Transceivers

- 32G power optimized for edge applications
- 58G PAM4 in mainstream devices
- 112G PAM4—Industry's highest performance

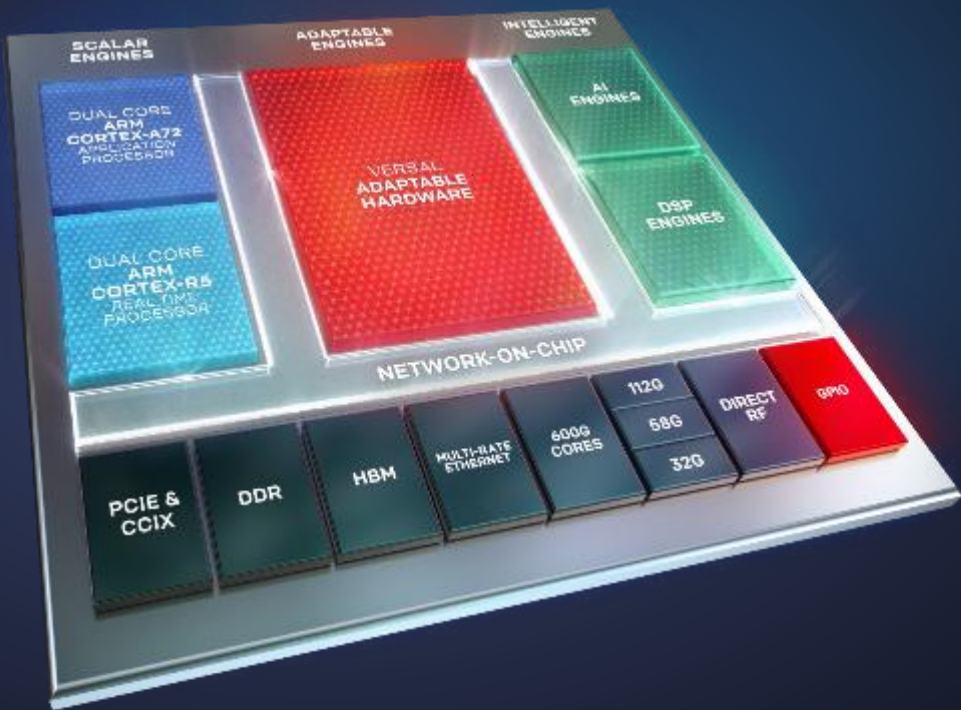




Integrated RF Signal Chain

- Next-generation multi-GSPS direct RF-ADC/DAC
- Integrated DDC/DUC
- SD-FEC for 5G and DOCSIS

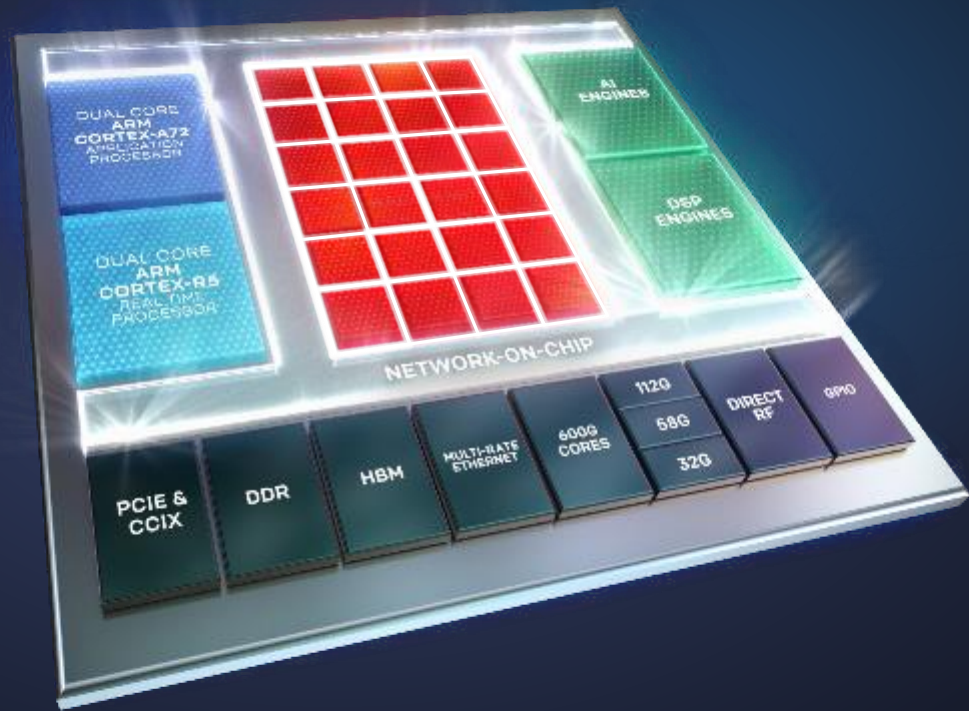




Programmable I/O Interfaces

- MIPI D-PHY >3Gb/s for sensors
- NAND and storage-class memory
- LVDS and general-purpose I/O





Network-on-Chip (NoC)

Ease of Use

Inherently software programmable
Available at boot, no place-and-route required

High Bandwidth and Low Latency

Multi-terabit/sec throughput
Guaranteed QoS

Power Efficiency

8X power efficiency vs. soft implementations
Arbitration across heterogeneous engines





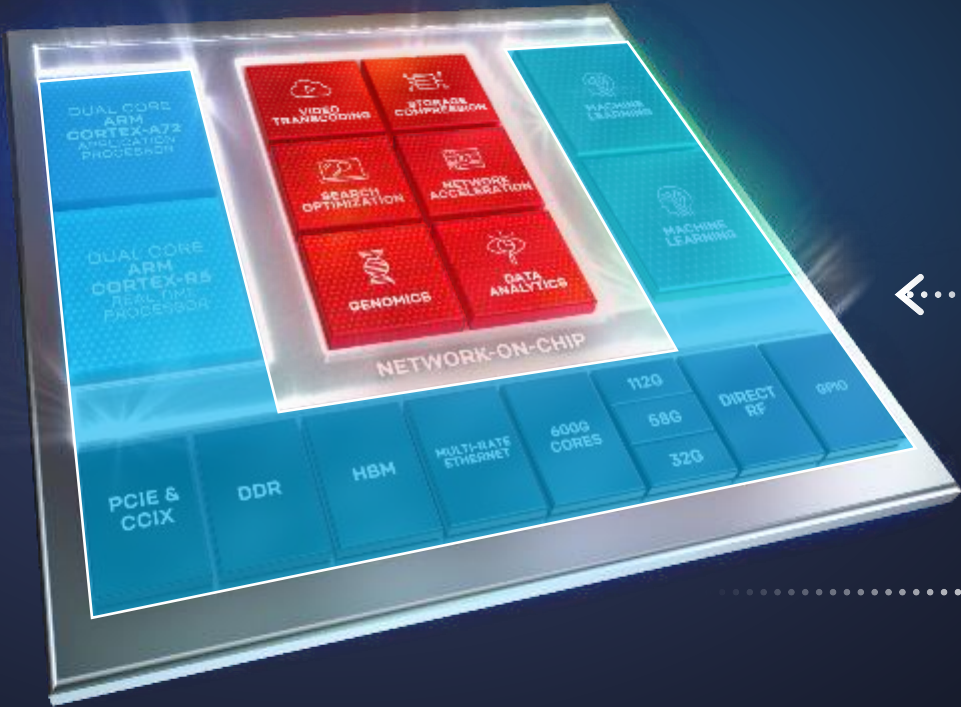
NoC Enables Software Programmability



Data Transfer between Engines and Memory



NoC Enables Software Programmability

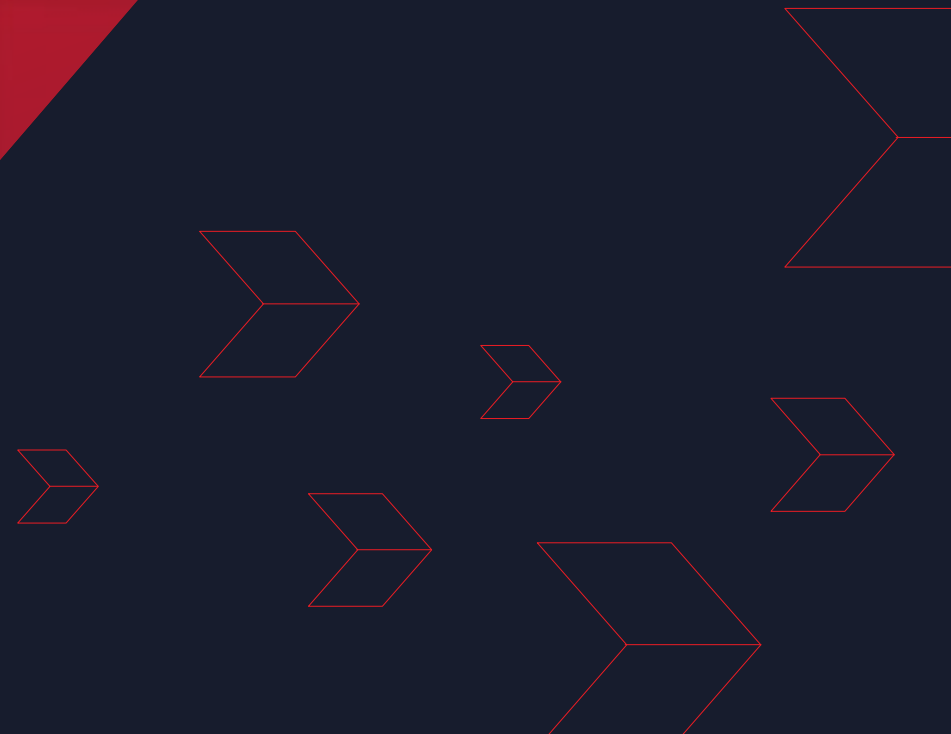


Data Transfer between Engines and Memory



Seamless Integration

**For Any
Application**



➤ Versal for Multi-Market Applications



CLOUD



Data Center



NETWORK



Wired



EDGE



Wireless



Endpoints

AI ADOPTION ACROSS MARKETS



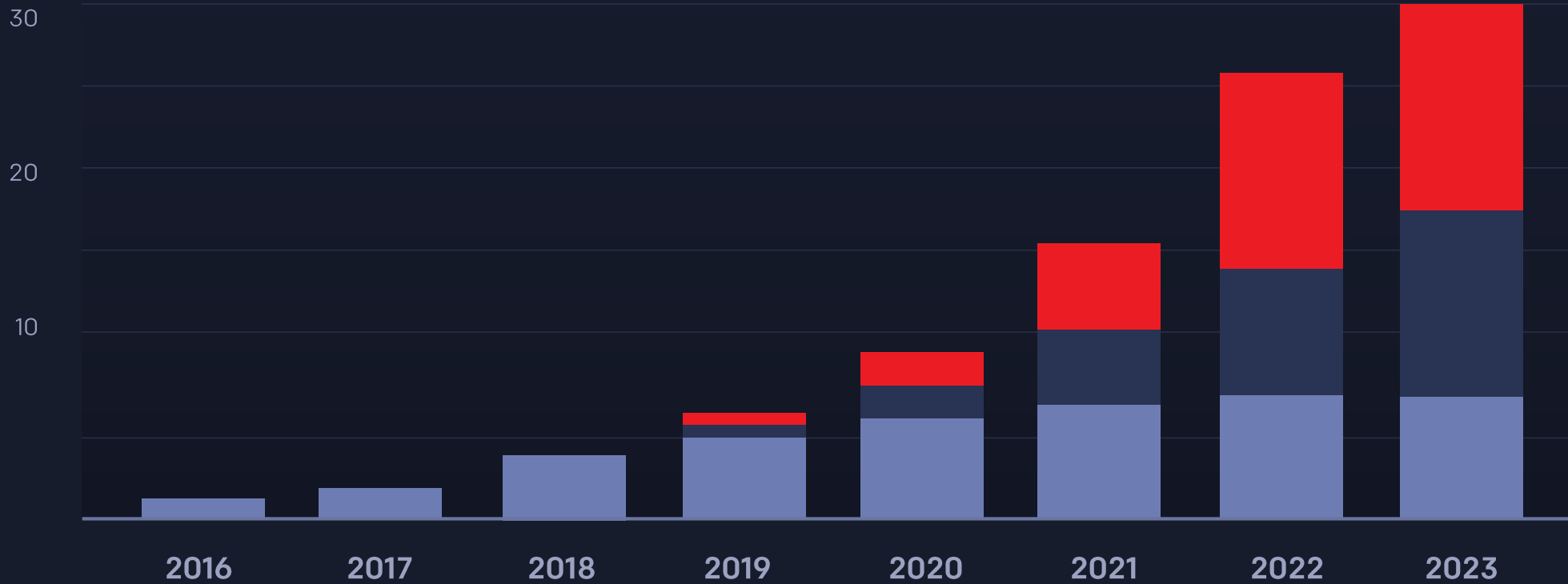
➤ Pervasiveness of AI and Inference

Semi
TAM \$B

Training

Data Center Inference

Edge Inference





XILINX[®]
VERSAL[™]



AI Edge
Series



AI Core
Series



AI RF
Series



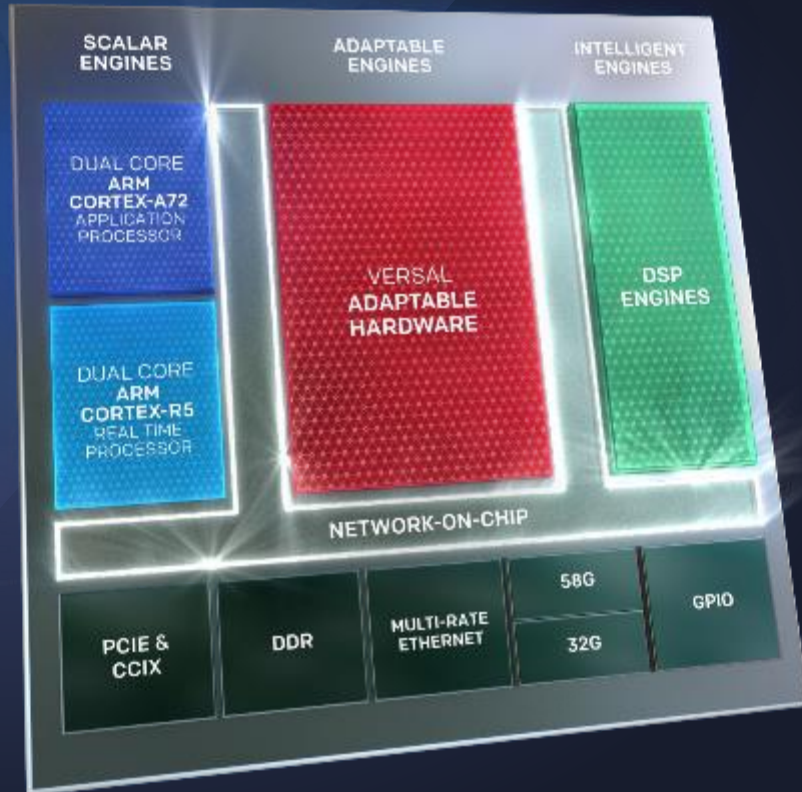
Prime
Series



Premium
Series



HBM
Series



VERSAL

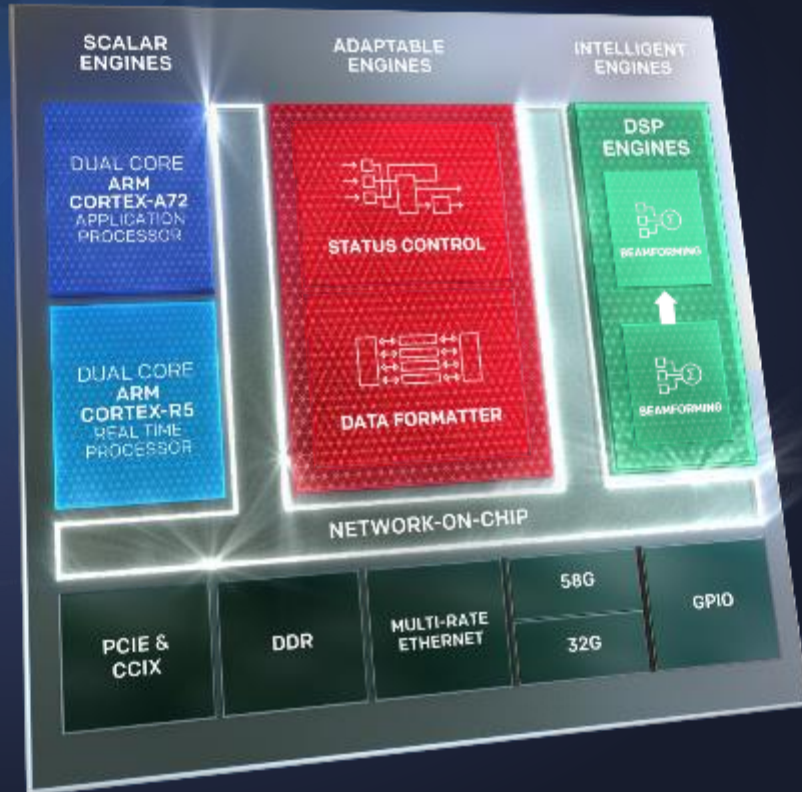
Prime Series

Broad Applicability Across Multiple Markets

Mid-range series in the Versal portfolio

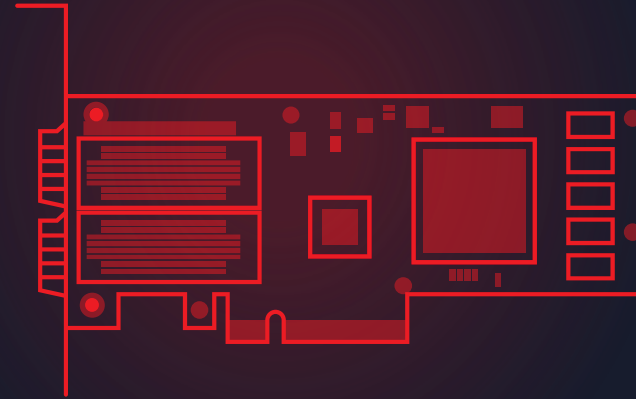
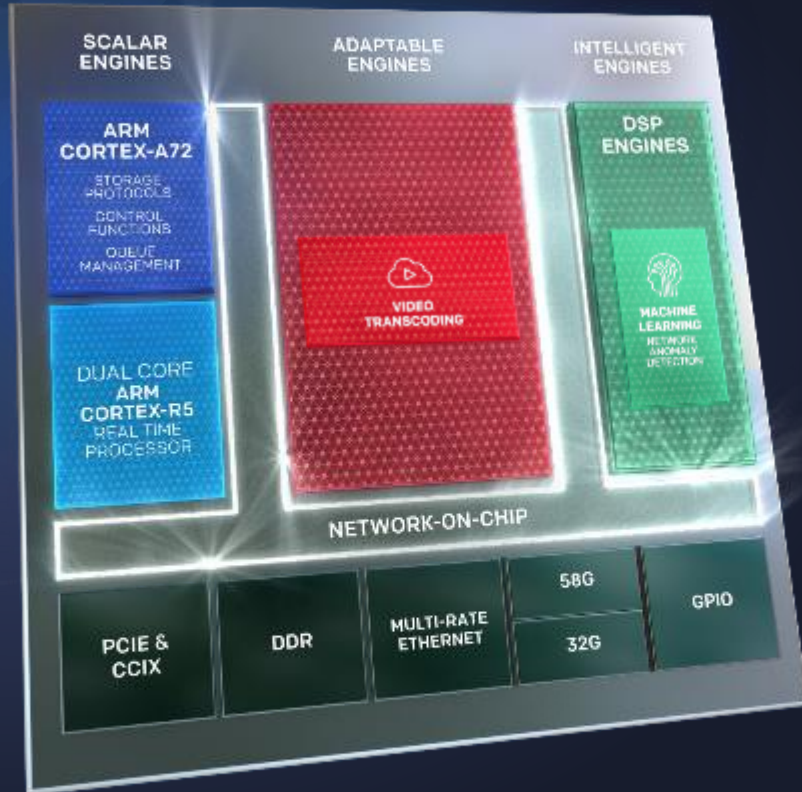
Optimized for connectivity

For inline acceleration and diverse workloads



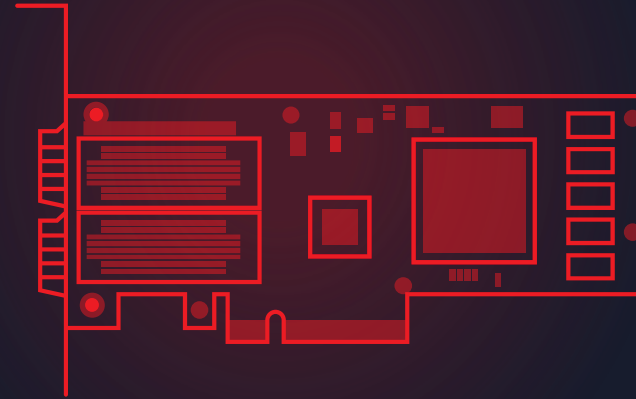
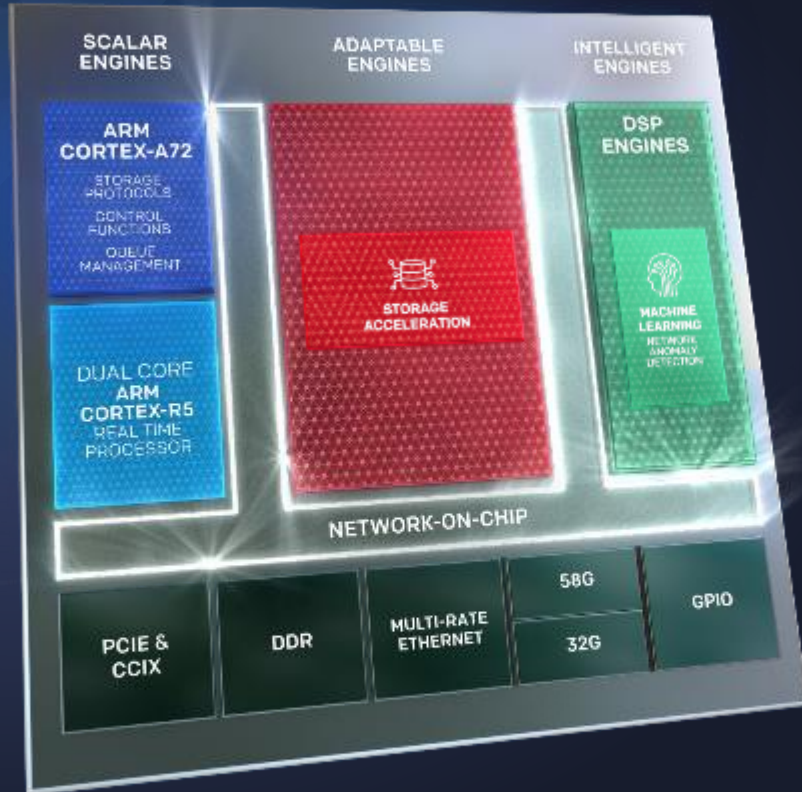
Versal Prime Series Intelligent Engines in Radar Beamforming

DSP Engines for diverse, fixed & floating point signal processing workloads



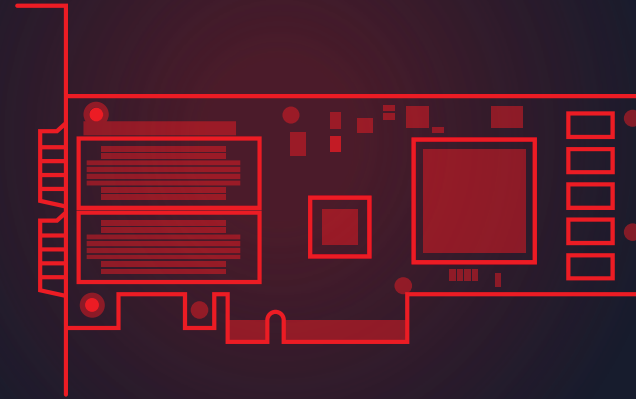
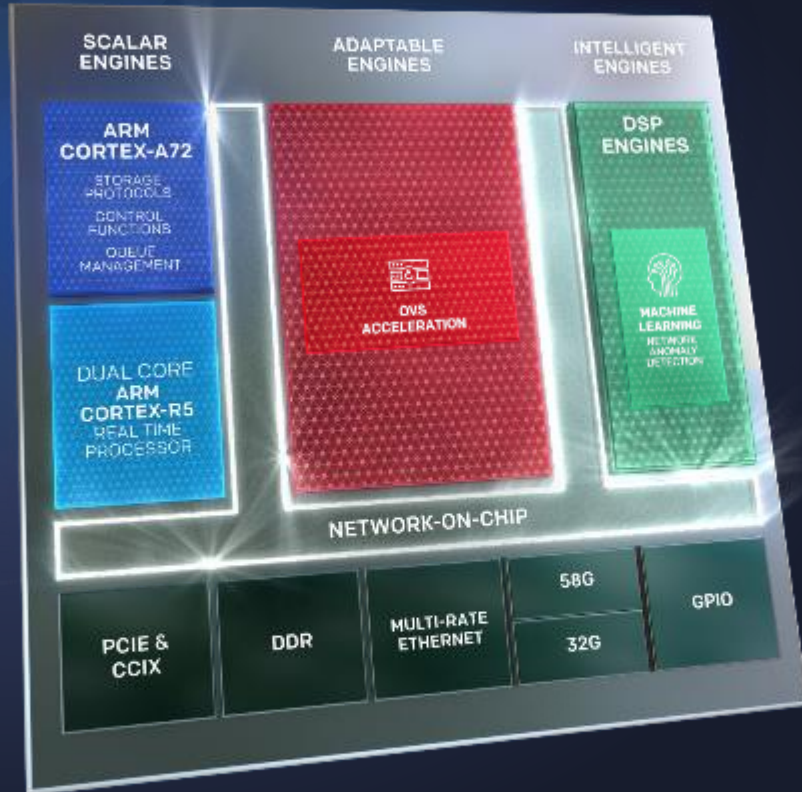
Network Attached Acceleration

Support for multiple network-attached workloads
Ability to combine workloads with AI inference



Network Attached Acceleration

Support for multiple network-attached workloads
Ability to combine workloads with AI inference



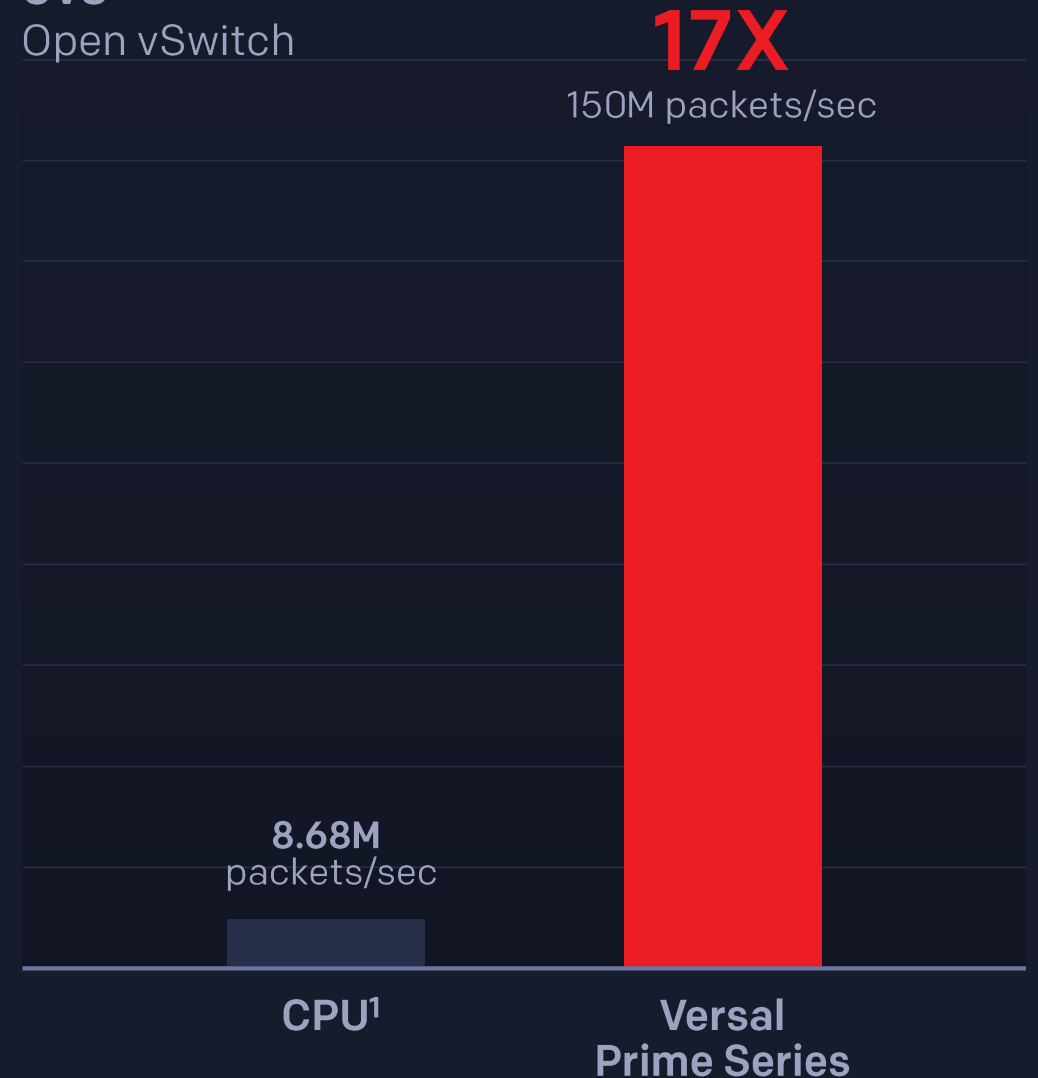
Network Attached Acceleration

Support for multiple network-attached workloads
Ability to combine workloads with AI inference

➤ Network Attached Accelerator Workloads

1: Assuming 4 Xeon cores at 2.17/Mp/s per core for zero packet loss;
Source: "Red Hat's Perspective on OVS HW Offload Status", Open vSwitch Fall Conference 2017

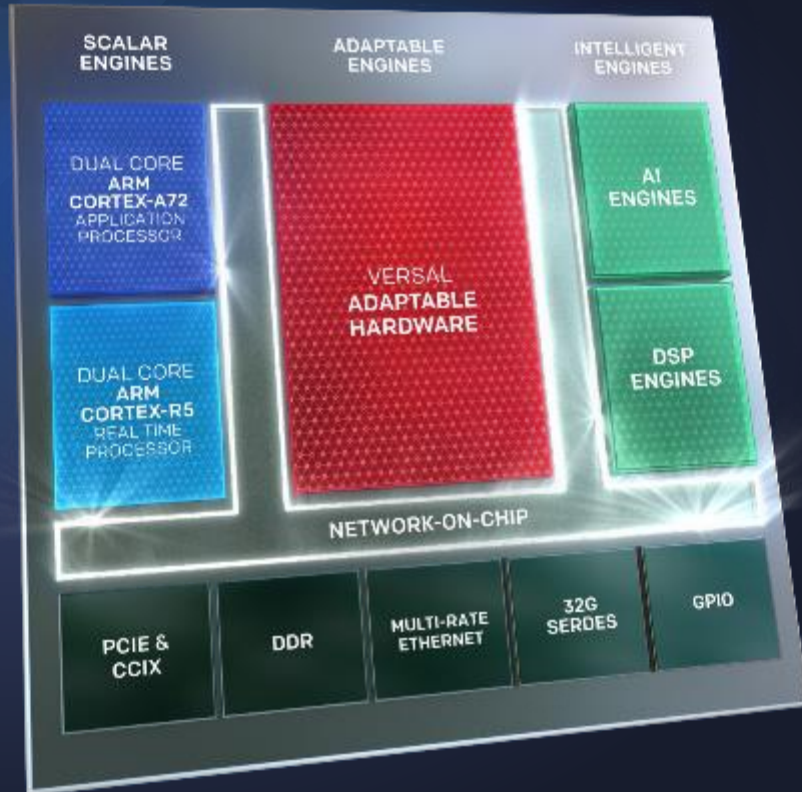
OVS
Open vSwitch



More Applications with Versal Prime Series

- Communications Test Equipment
- Data Center Network and Storage Acceleration
- Nx100G Ethernet and OTN Networking
- Broadcast Switches
- Medical Imaging
- Avionics Control





VERSAL

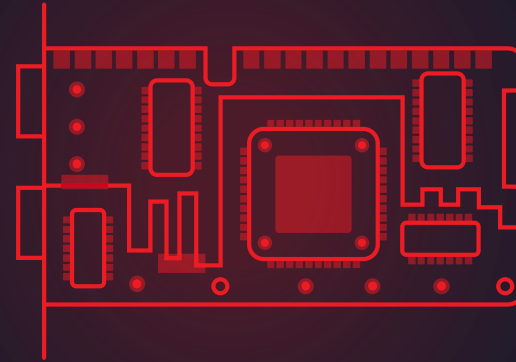
AI Core Series

Breakthrough AI Inference Throughput

Portfolio's highest throughput for low latency inference

Optimized for cloud, networking, and autonomous applications

For highest dynamic range of AI and workload acceleration

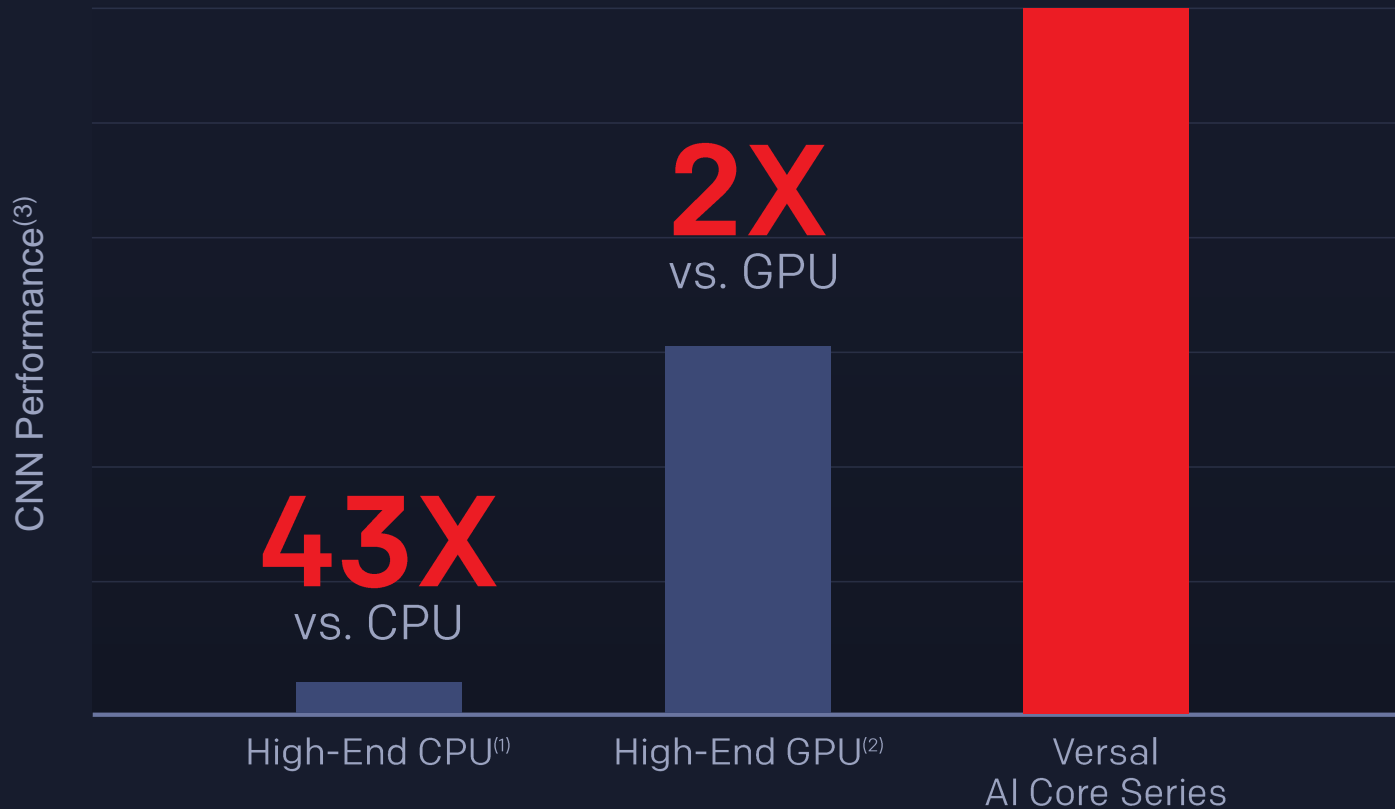


VERSAL AI Core Series AI Engines and Adaptable Hardware Maximize AI Inference

Massive bandwidth across heterogeneous engines for optimal performance

➤ AI Compute Compared to CPUs and GPUs

High Batch (Latency Insensitive)



Inference Performance

Leveraging AI Engines
Majority of Adaptable & Scalar Engines available for Whole Application Acceleration

Whole Application Acceleration

Ability to combine workloads and trade-off resources between AI and workload

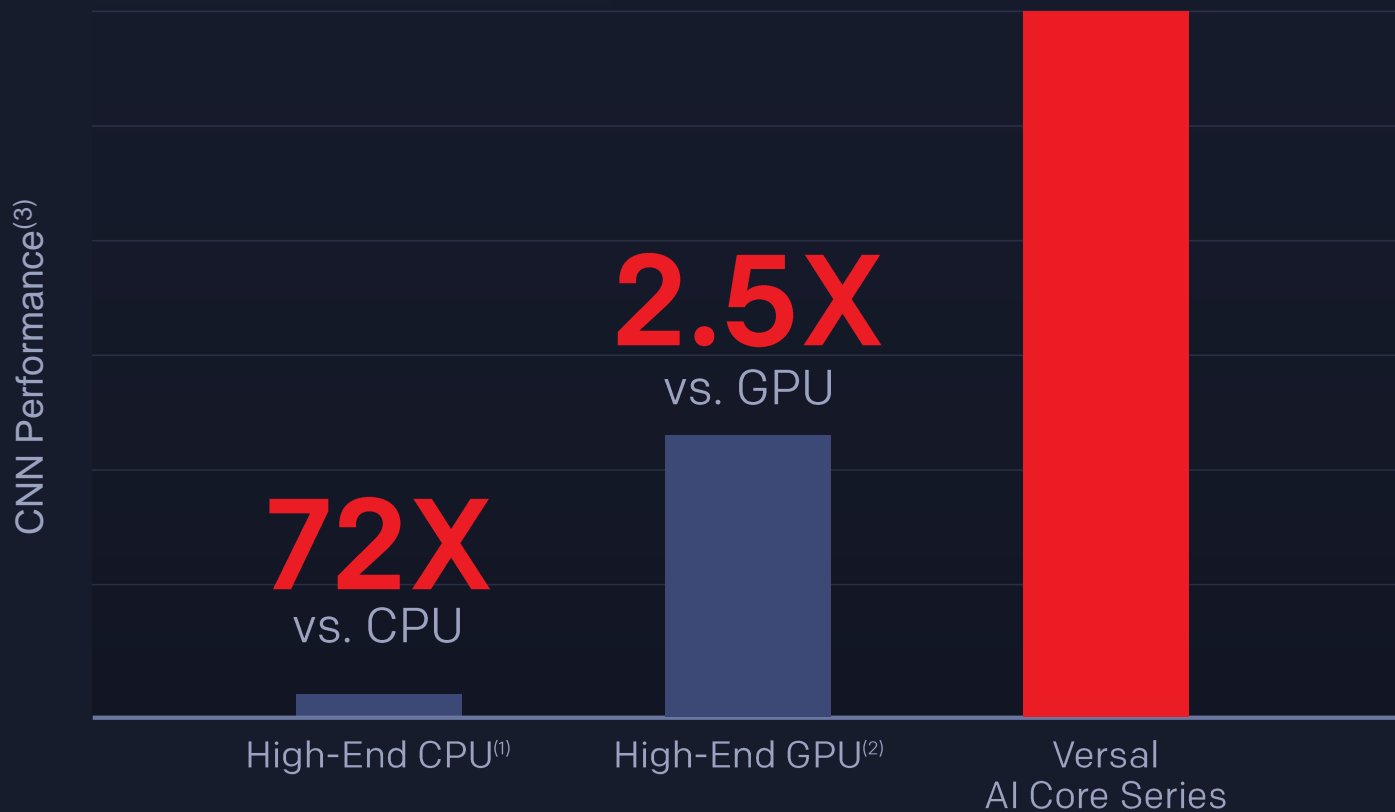
(1) Measured on EC2 Xeon Platinum 8124 Skylake, c5.18xlarge AWS instance, Intel Caffe: <https://github.com/intel/caffe>

(2) V100 numbers taken from Nvidia Technical Overview, "Deep Learning Platform, Giant Leaps in Performance and Efficiency for AI Services"

(3) GoogLeNet V1 throughput (Img/sec)

➤ AI Compute Compared to CPUs and GPUs

Sub – 7ms Latency



Inference Performance

Leveraging AI Engines

Majority of Adaptable & Scalar Engines available for Whole Application Acceleration

Whole Application Acceleration

Ability to combine workloads and trade-off resources between AI and workload

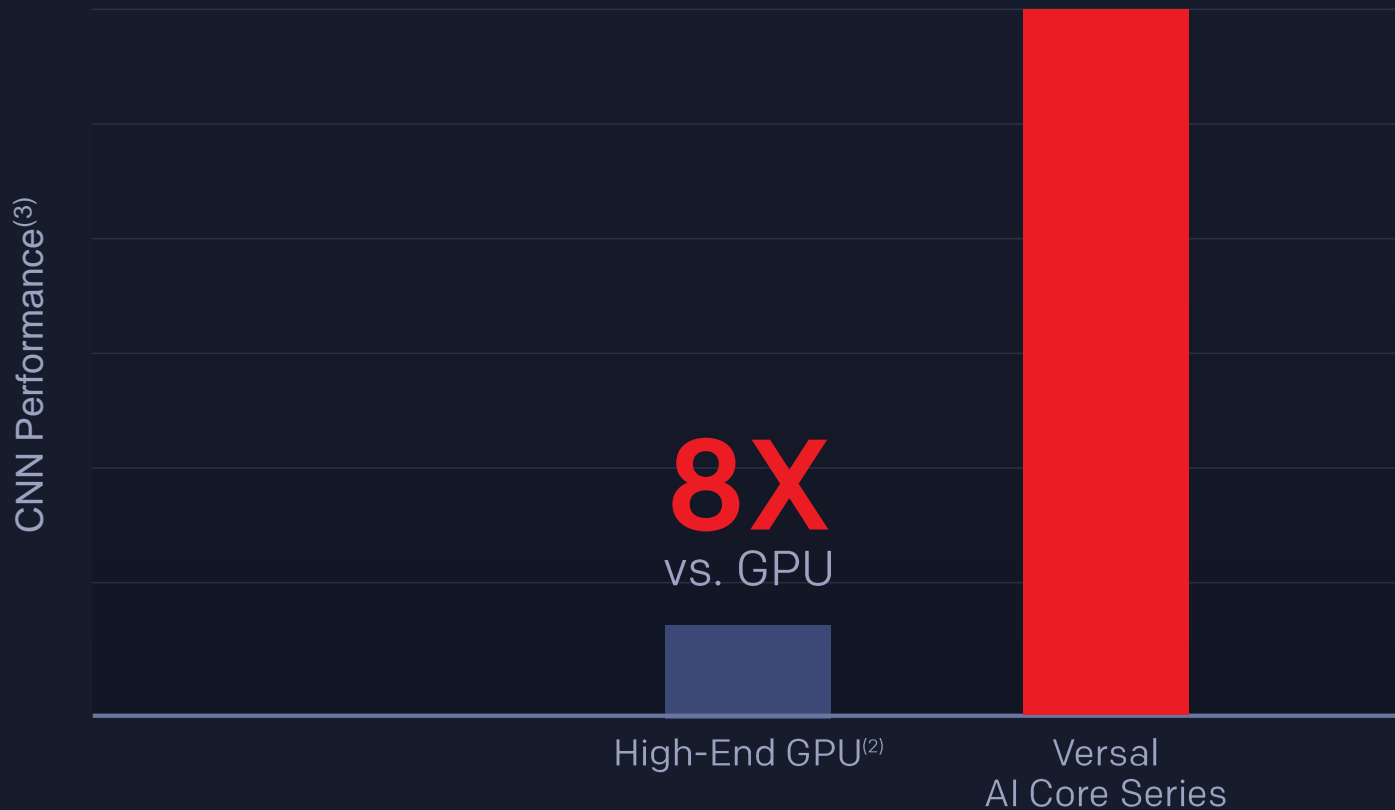
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(2) V100 numbers taken from Nvidia Technical Overview, "Deep Learning Platform, Giant Leaps in Performance and Efficiency for AI Services"

(3) GoogLeNet V1 throughput (Img/sec)

➤ AI Compute Compared to CPUs and GPUs

Sub – 2ms Latency



Inference Performance

Leveraging AI Engines

Majority of Adaptable & Scalar Engines available for Whole Application Acceleration

Whole Application Acceleration

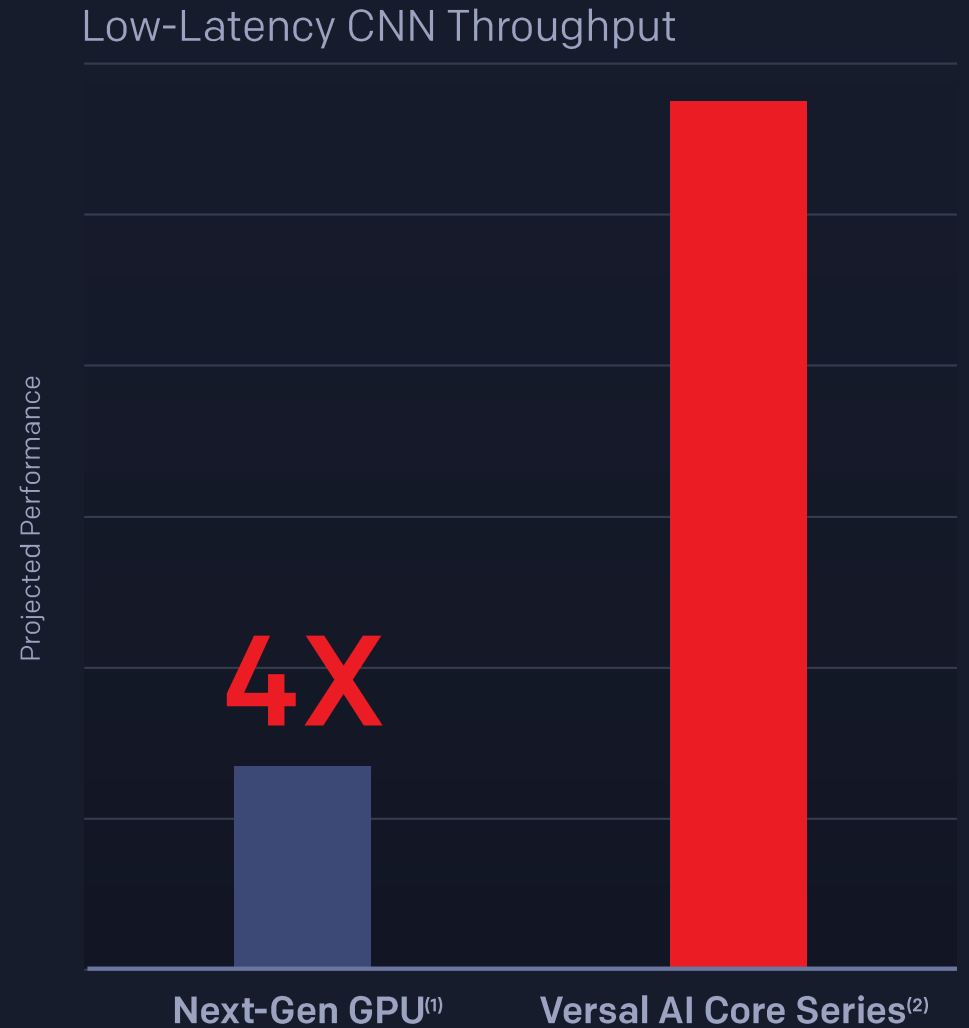
Ability to combine workloads and trade-off resources between AI and workload

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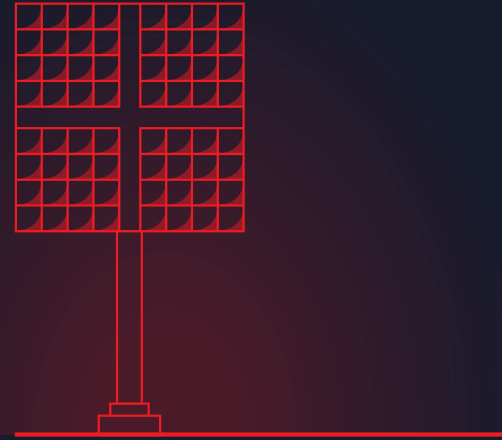
➤ AI Inference Power Efficiency Advantage over GPUs

4X the Throughput in the Same
Power Envelope (75W)



(1) 12-nanometer T4 GPU device, Projected Batch=1 performance based on currently available vendor benchmarks

(2) 7-nanometer Xilinx Versal ACAP device, Latency ~500us



VERSAL AI Core Series For 5G Wireless Compute with AI Inference

AI Engines have ability to combine inference with wireless compute

➤ Mixed Workloads on AI Engine



5X

MAX Wireless Compute¹

- Systolic Array
- CloudRAN
- Baseband Processing

UNDER DEVELOPER CONTROL
Combine Workloads on AI Engine



8X

MAX AI Inference¹

- Self-Organizing Networks
- Anomaly Detection
- Scheduling

1: Compared to UltraScale+



➤ Mixed Workloads on AI Engine



5X

MAX Wireless Compute¹

- Systolic Array
- CloudRAN
- Baseband Processing

UNDER DEVELOPER CONTROL
Combine Workloads on AI Engine



8X

MAX AI Inference¹

- Self-Organizing Networks
- Anomaly Detection
- Scheduling






1: Compared to UltraScale+



**For Any
Developer**



➤ Comprehensive Tool Chain

TOOLS	USER	SUPPORTED ENTRY METHODS
Frameworks	Data Scientists & AI Developers	 TensorFlow  Caffe  mxnet  Spark  FFmpeg
New Unified Software Development Environment	Application Developers	
Embedded Run-Time	Embedded Developers	 Linux  Xen  FreeRTOS
Vivado Design Suite	Hardware Developers	

Versal Development Experience

Adaptable For
Any Application

User Application
C, C++, Python

Application-Specific Frameworks

Machine Learning | Video | Genomics | Search | Financial Modeling | Database

Software
Programmable

New Unified Software Development Environment

OS & Embedded Run-Time

Custom HW

Xilinx & Ecosystem
HW Libraries

C, Xilinx Libraries

Heterogeneous
Platform

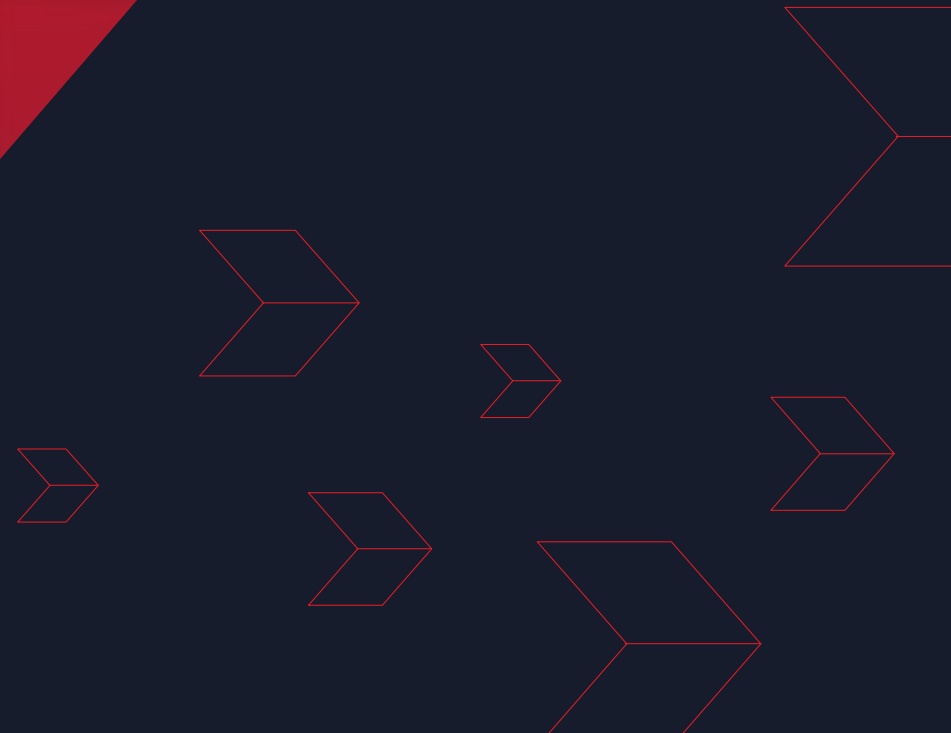
Scalar Engines

Adaptable Engines

Intelligent Engines

VERSAL

What's Ahead





XILINX®
VERSAL™



AI Edge
Series



AI Core
Series



AI RF
Series



Prime
Series



Premium
Series



HBM
Series

Versal Roadmap



AI Core
AI Inference
Throughout



Prime
Broadest
Application



Premium
112G Serdes
600G Cores



AI Edge
Lowest
power AI



AI RF
AI w/
Integrated RF



HBM
Memory
Integration

2H 2019

2020

2021

IN SUMMARY

➤ **Versal ACAP** ➤ **Delivers**

Heterogeneous
Acceleration

For Any Application

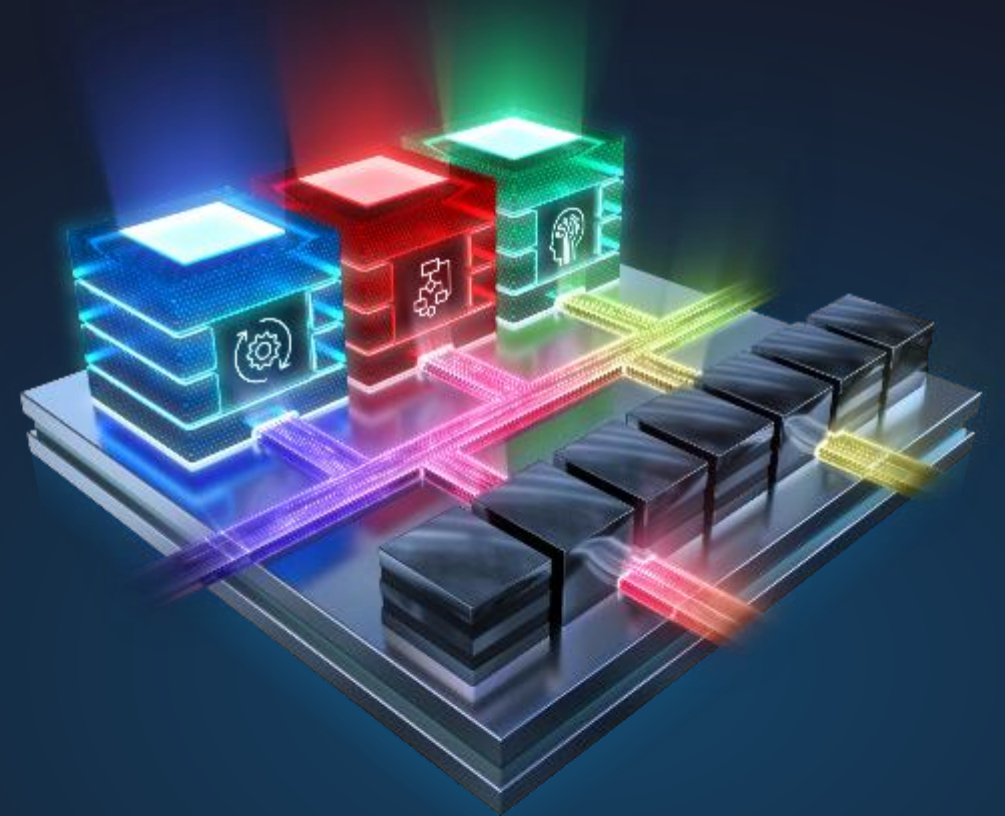
For Any Developer

Disruptive Innovation

Software Programmability

Hardware Adaptability

Whole Application
Acceleration



**Adaptable
Intelligent**



Versal Prime Series — Resources

		VM1102	VM1302	VM1402	VM1502	VM1802	VM2502	VM2602	VM2702	VM2902
Intelligent Engines	DSP Engines	472	736	1,504	1,312	1,968	3,984	1,880	2,500	3,080
	Adaptable Engines									
Memory	System Logic Cells (K)	352	572	1,002	797	1,968	2,030	1,263	1,805	2,154
	LUTs	161,024	261,376	457,984	364,544	899,840	927,872	577,536	825,000	984,576
	Distributed RAM (Mb)	5	8	14	11	27	28	18	25	30
Scalar Engines	Total Block RAM (Mb)	8	16	40	19	34	48	55	74	90
	Total UltraRAM (Mb)	27	47	47	60	130	197	119	169	204
	Total SRAM Capacity (Mb)	35	63	87	80	164	245	174	243	294
Foundational Platform	Application Processing Unit	Dual-core Arm® Cortex-A72, 48KB/32KB L1 Cache w/ parity & ECC; 1MB L2 Cache w/ ECC								
	Real-time Processing Unit	Dual-core Arm Cortex-R5, 32KB/32KB L1 Cache, and 256KB TCM w/ECC								
	Memory	256KB On-Chip Memory w/ECC								
	Connectivity	Ethernet (x2); USB 2.0 (x1); UART (x2); SPI (x2); I2C (x2); CAN-FD (x2)								
Foundational Platform	NoC Master / NoC Slave Ports	5	16	16	14	28	28	16	26	26
	DDR Bus Widths	64	128	256	128	256	288	384	384	384
	DDR Memory Controllers	1	2	4	2	4	5	6	6	6
	CCIX & PCIe® w/DMA (CPM)	-	-	-	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX
	PCI Express®	1 x Gen4x8	2 x Gen4x8	2 x Gen4x8	4 x Gen4x8	4 x Gen4x8	1 x Gen4x8	1 x Gen4x8	2 x Gen4x8	2 x Gen4x8
	Multirate Ethernet MAC	1	2	2	4	4	1	2	2	2
Package Footprint	Package Dimensions	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM	XPIO, HDIO, MIO GTY, GTM
B625	21x21	216, 22, 78, 4, 0								
B1024	31x31	216, 22, 78, 12, 0		216, 44, 78, 16, 0		324, 44, 78, 16, 0				
B1369	35x35	216, 44, 78, 24, 0		324, 44, 78, 24, 0		324, 44, 78, 24, 0				
A1760	40x40	432, 44, 78, 24, 0		648, 44, 78, 24, 0				756, 22, 78, 20, 0		
C1760	40x40			378, 44, 78, 44, 0		378, 44, 78, 44, 0		378, 22, 78, 20, 32		378, 44, 78, 24, 32
D1760	40x40					648, 44, 78, 24, 0				
A2197	45x45					648, 44, 78, 44, 0		648, 44, 78, 16, 16		
A2785	50x50							702, 44, 78, 16, 28		702, 22, 78, 20, 32
								702, 44, 78, 32, 44		702, 44, 78, 40, 52

All parameters listed are maximum values. Verify all data in this document with the device data sheets or product guides found at: www.xilinx.com.

➤ Versal AI Core Series — Resources

		VC1352	VC1502	VC1702	VC1802	VC1902	
Intelligent Engines	AI Engines	128	217	310	300	400	
	AI Engine Data Memory Blocks (#)	1024	1736	2480	2400	3200	
	AI Engine Data Memory (Mb)	32	54.25	77.5	75	100	
	DSP Engines	928	1,312	1,272	1,600	1,968	
Adaptable Engines	System Logic Cells (K)	540	797	1,021	1,586	1,968	
	LUTs	246,784	364,544	466,688	725,000	899,840	
	Distributed RAM (Mb)	8	11	14	22	27	
Memory	Total Block RAM (Mb)	18	19	29	28	34	
	UltraRAM (Mb)	42	60	113	91	130	
	Accelerator RAM (Mb)	32	0	32	0	0	
	Total SRAM Capacity (Mb)	92	80	174	120	164	
Scalar Engines	Application Processing Unit	Dual-core Arm® Cortex-A72, 48KB/32KB L1 Cache w/ parity & ECC; 1MB L2 Cache w/ ECC					
	Real-time Processing Unit	Dual-core Arm Cortex-R5, 32KB/32KB L1 Cache, and 256KB TCM w/ECC					
	Memory	256KB On-Chip Memory w/ECC					
	Connectivity	Ethernet (x2); UART (x2); CAN-FD (x2); USB 2.0 (x1); SPI (x2); I2C (x2)					
Foundational Platform	NoC Master / NoC Slave Ports	10	14	18	28	28	
	DDR Bus Width	128	128	128	256	256	
	DDR Memory Controllers	2	2	2	4	4	
	CCIX & PCIe® w/DMA (CPM)	–	1 x Gen4x16, CCIX	–	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX	
	PCI Express®	1 x Gen4x8	4 x Gen4x8	1 x Gen4x8	4 x Gen4x8	4 x Gen4x8	
	Multirate Ethernet MAC	1	4	3	4	4	
	SD-FEC	2	0	5	0	0	
	Platform Management Controller	Boot, Security, Safety, Monitoring, and High Speed Debug					
Package Footprint	Package Dimensions	Ball Pitch		XPIO, HDIO, MIO, GTY		XPIO, HDIO, MIO, GTY	
	A1024	31x31	0.92	378, 22, 78, 8		378, 22, 78, 8	
E1369	35x35	0.92	378, 44, 78, 8		378, 44, 78, 24		
A1596	37.5x37.5	0.92	378, 44, 78, 32		378, 44, 78, 16		
D1760	40x40	0.92			378, 44, 78, 32		
A2197	45x45	0.92	378, 44, 78, 44		648, 44, 78, 44		
					648, 44, 78, 44		
					648, 44, 78, 44		

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